To all our customers

Regarding the change of names mentioned in the document, such as Hitachi Electric and Hitachi XX, to Renesas Technology Corp.

The semiconductor operations of Mitsubishi Electric and Hitachi were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Hitachi, Hitachi, Ltd., Hitachi Semiconductors, and other Hitachi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

Renesas Technology Home Page: http://www.renesas.com

Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.
   Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

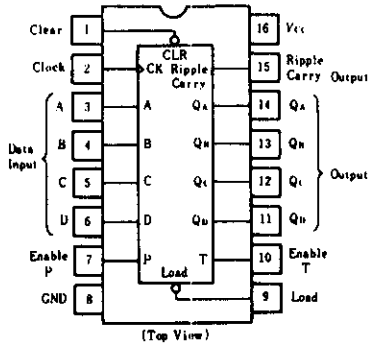
Notes regarding these materials

1. These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corporation product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corporation or a third party.
2. Renesas Technology Corporation assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corporation without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corporation or an authorized Renesas Technology Corporation product distributor for the latest product information before purchasing a product listed herein.
   The information described here may contain technical inaccuracies or typographical errors.
   Renesas Technology Corporation assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.
   Please also pay attention to information published by Renesas Technology Corporation by various means, including the Renesas Technology Corporation Semiconductor home page (http://www.renesas.com).
4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corporation assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
5. Renesas Technology Corporation semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corporation or an authorized Renesas Technology Corporation product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
6. The prior written approval of Renesas Technology Corporation is necessary to reprint or reproduce in whole or in part these materials.
7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
   Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
8. Please contact Renesas Technology Corporation for further details on these materials or the products contained therein.

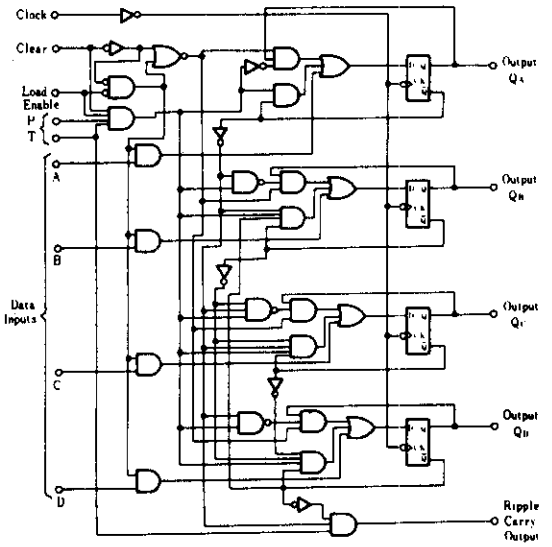
HD74LS162A ● Synchronous Decade Counters (synchronous clear)

This synchronous decade counter features an internal carry look-ahead for application in high-speed counting designs. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable inputs and internal gating. This mode of operation eliminates the output counting spikes that are normally associated with asynchronous (ripple clock) counters. A buffered clock input triggers the four flip-flops on the rising (positive-going) edge of the clock input waveform. This counter is fully programmable; that is, the outputs may be preset to either level. As preseting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse regardless of the levels of the enable inputs. Low-to-high transitions at the load input should be avoided when the clock is low if the enable inputs are high at or before the transition. The clear function is synchronous and a low level at the clear input sets all four of the flip-flop outputs low after the next clock pulse, regardless of the levels of the enable inputs. This synchronous clear allows the count length to be modified easily as decoding the maximum count desired can be accomplished with one external NAND gate. The gate output is connected to the clear input to synchronously clear the counter to LLLL. Low-to-high transitions at the clear input should be avoided when the clock is low if the enable and load inputs are high at or before the transition. The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Instrumental in accomplishing this function are two count-enable inputs and a ripple carry output. Both count-enable inputs (P and T) must be high to count, and input T is fed forward to enable the ripple carry output. The ripple carry output thus enabled will produce a high-level output pulse with a duration approximately equal to the high-level portion of the Q_A output. This high-level overflow ripple carry pulse can be used to enable successive cascaded stages. High-to-low-level transitions at the enable P or T inputs should occur only when the clock input is high.

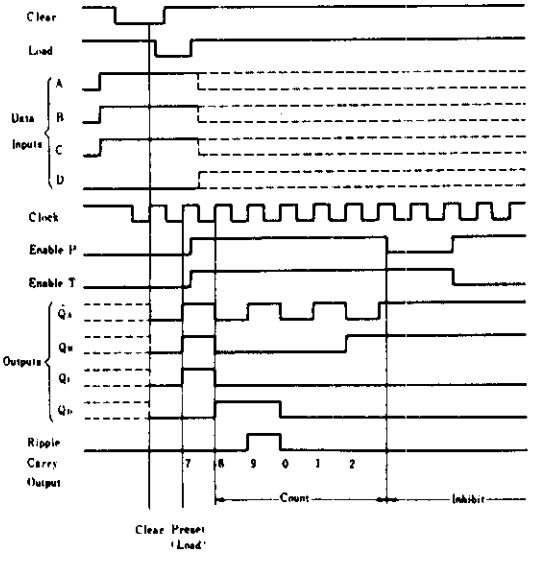
■PIN ARRANGEMENT



■BLOCK DIAGRAM



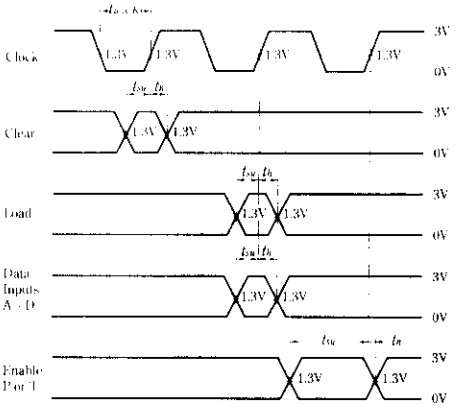
■TYPICAL CLEAR, PRESET, AND INHIBIT SEQUENCE



■RECOMMENDED OPERATING CONDITIONS

Item		Symbol	min	typ	max	Unit
Clock frequency		f_{clock}	0	—	25	MHz
Clock pulse width		$t_{w(CK)}$	25	—	—	ns
Clear pulse width		$t_{w(CLR)}$	20	—	—	ns
Setup time	A, B, C, D	t_{su}	20	—	—	ns
	Enable P, T		20	—	—	ns
	Load		20	—	—	ns
	Clear		20	—	—	ns
Hold time		t_h	3	—	—	ns

■TIMING DEFINITION



■ELECTRICAL CHARACTERISTICS ($Ta = -20 \sim +75°C$)

Item		Symbol	Test Conditions		min	typ*	max	Unit
Input voltage		V_{IH}			2.0	—	—	V
		V_{IL}			—	—	0.8	V
Output voltage		V_{OH}	V_{CC} = 4.75V, V_{IH} = 2V, V_{IL} = 0.8V, I_{OH} = −400μA		2.7	—	—	V
		V_{OL}	V_{CC} = 4.75V, V_{IH} = 2V, V_{IL} = 0.8V	I_{OL} = 4mA	—	—	0.4	V
				I_{OL} = 8mA	—	—	0.5	
Input current	Data, Enable P	I_{IH}	V_{CC} = 5.25V, V_I = 2.7V		—	—	20	μA
	Load, Clock, Enable T				—	—	40	
	Clear				—	—	40	
	Data, Enable P	I_{IL}	V_{CC} = 5.25V, V_I = 0.4V		—	—	−0.4	mA
	Load, Clock, Enable T				—	—	−0.8	
	Clear				—	—	−0.8	
	Data, Enable P	I_I	V_{CC} = 5.25V, V_I = 7V		—	—	0.1	mA
	Load, Clock, Enable T				—	—	0.2	
	Clear				—	—	0.2	
Short-circuit output current		I_{OS}	V_{CC} = 5.25V		−20	—	−100	mA
Supply current**		I_{CCH}	V_{CC} = 5.25V		—	18	31	mA
		I_{CCL}	V_{CC} = 5.25V		—	19	32	mA
Input clamp voltage		V_{IK}	V_{CC} = 4.75V, I_{IN} = −18mA		—	—	−1.5	V

* V_{CC}=5V, Ta=25°C

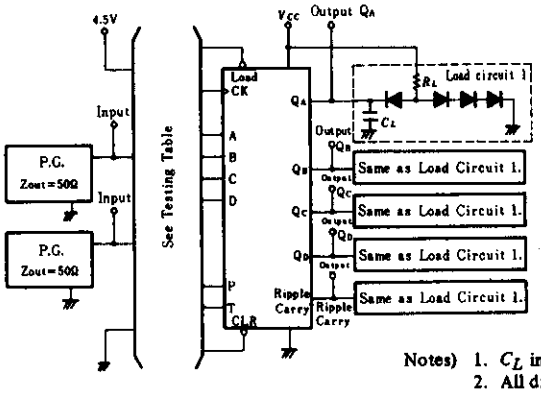
** I_{CCH} is measured with the load input high, then again with the load input low, with all other inputs high and all outputs open. I_{CCL} is measured with the clock input high, then again with the clock input low, with all other inputs low and all outputs open.

■SWITCHING CHARACTERISTICS (V_{CC} = 5V, Ta = 25°C)

Item	Symbol	Inputs	Outputs	Test Conditions	min	typ	max	Unit
Maximum clock frequency	f_{max}	Clock	$Q_A \sim Q_D$	C_L = 15pF, R_L = 2kΩ	25	32		MHz
Propagation delay time	t_{PLH}	Clock	Ripple Carry		—	20	35	ns
	t_{PHL}				—	18	35	ns
	t_{PLH}	Clock (Load="H")	$Q_A \sim Q_D$		—	13	24	ns
	t_{PHL}				—	18	27	ns
	t_{PLH}	Clock (Load="L")	$Q_A \sim Q_D$		—	13	24	ns
	t_{PHL}				—	18	27	ns
	t_{PLH}	Enable T	Ripple Carry		—	9	14	ns
	t_{PHL}				—	9	14	ns
	t_{PHL}	Clear	$Q_A \sim Q_D$		—	20	28	ns

■TESTING METHOD

1) Test Circuit



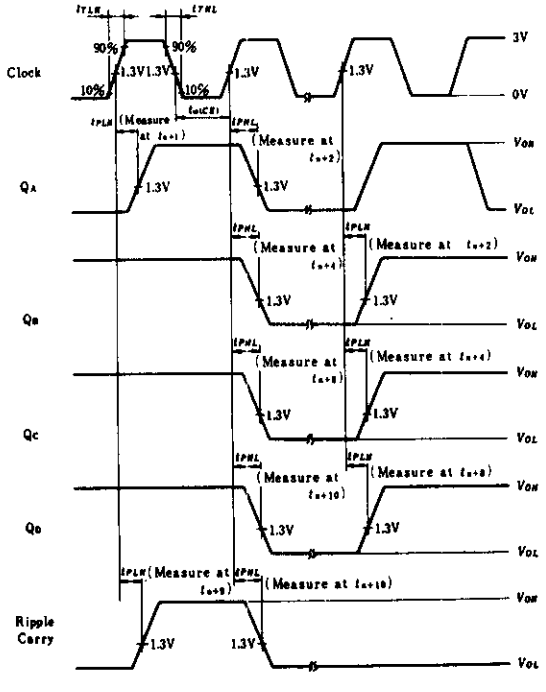
Notes) 1. C_L includes probe and jig capacitance.
2. All diodes are 1S2074 Ⓗ

2) Testing Table

Item	From input to output	Inputs									Outputs				
		Clear	Load	Enable P	Enable T	Clock	Data A	Data B	Data C	Data D	Q_A	Q_B	Q_C	Q_D	Ripple Carry
f_{max}		4.5V	4.5V	4.5V	4.5V	IN	GND	GND	GND	GND	OUT	OUT	OUT	OUT	OUT
t_{PLH} t_{PHL}	CK→Ripple Carry	4.5V	4.5V	4.5V	4.5V	IN	GND	GND	GND	GND	–	–	–	–	OUT
	CK→Q	4.5V	4.5V	4.5V	4.5V	IN	GND	GND	GND	GND	OUT	OUT	OUT	OUT	–
	CK→Q	4.5V	GND	GND	GND	IN	IN*	IN*	IN*	IN*	OUT	OUT	OUT	OUT	–
	Enable T→Ripple Carry	4.5V	GND	4.5V	IN	IN**	4.5V	GND	GND	4.5V	–	–	–	–	OUT
	Clear→Q	IN	GND	GND	GND	IN**	4.5V	4.5V	4.5V	4.5V	OUT	OUT	OUT	OUT	–

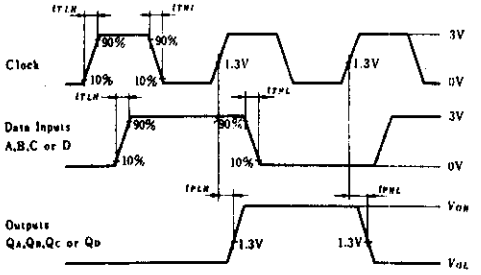
* Measuring outputs correspond to this condition, each outputs (Q_A, Q_B, Q_C, and Q_D) must not be over the following rate, "H", "L", "L", and 'H".
** For initialized

3) Waveform−1 f_{max}, t_{PLH}, t_{PHL} (Clock→Q, Ripple Carry)



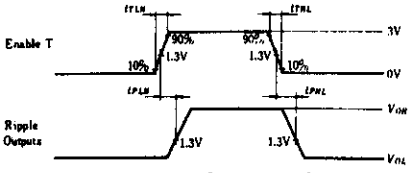
Notes) 1. Clock input pulse; t_{TLH}≦15ns, t_{THL}≦6ns, PRR=1MHz, duty cycle=50% and: for f_{max}, t_{TLH}=t_{THL}≦2.5ns.
2. t_n is reference bit time when all outputs are low.

Waveform−2 t_{PLH}, t_{PHL} (Clock→Q)



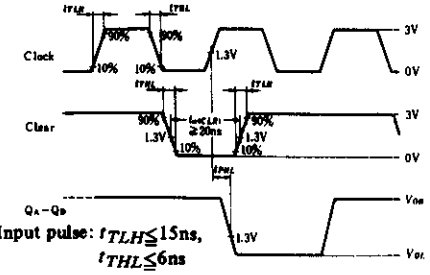
Notes) Input pulse: t_{TLH}≦15ns, t_{THL}≦6ns, Clock input: PRR= 1MHz, duty cycle 50%, Data input: PRR=500kHz, duty cycle 50%

Waveform−3 t_{PLH}, t_{PHL} (Enable T→Ripple Carry)



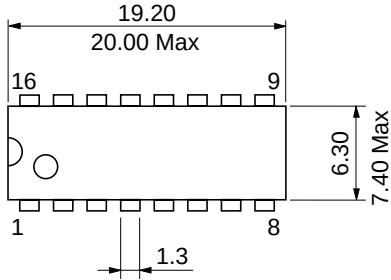
Note) Input pulse: t_{TLH}≦15ns, t_{THL}≦6ns, PRR=1MHz

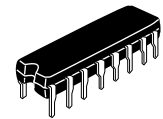
Waveform−4 t_{PHL} (Clear→Q)

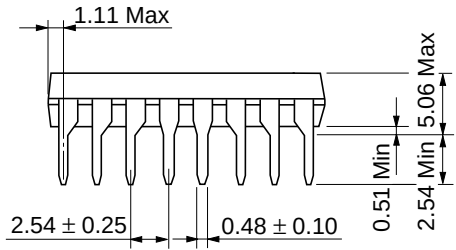


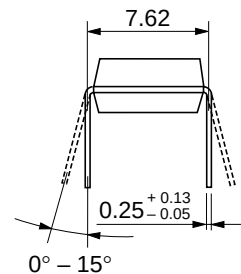
Note) Input pulse: t_{TLH}≦15ns, t_{THL}≦6ns

Unit: mm



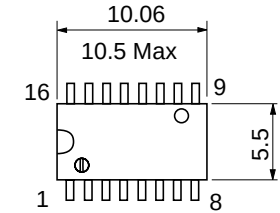


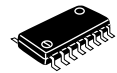


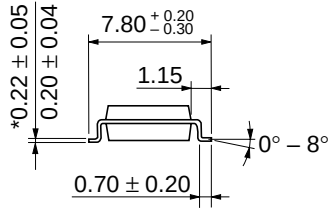


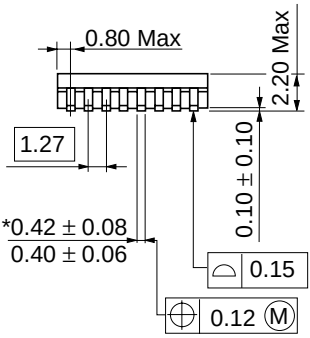
Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.07 g

Unit: mm





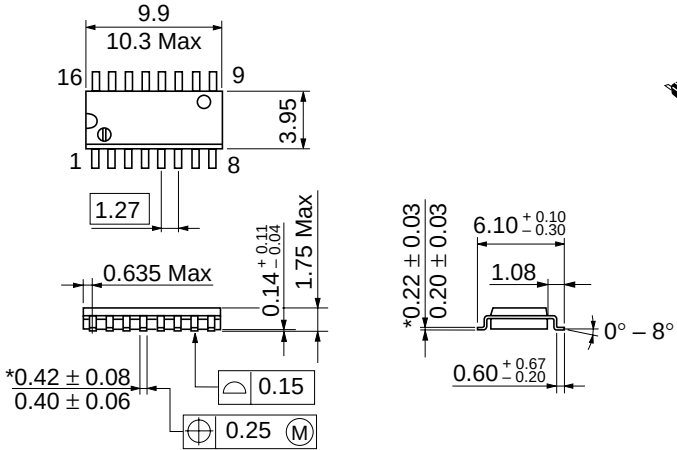


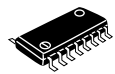


*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.24 g

Unit: mm





Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

*Dimension including the plating thickness
Base material dimension

Cautions

1. Hitachi neither warrants nor grants licenses of any rights of Hitachi's or any third party's patent, copyright, trademark, or other intellectual property rights for information contained in this document. Hitachi bears no responsibility for problems that may arise with third party's rights, including intellectual property rights, in connection with use of the information contained in this document.
2. Products and product specifications may be subject to change without notice. Confirm that you have received the latest product standards or specifications before final design, purchase or use.
3. Hitachi makes every attempt to ensure that its products are of high quality and reliability. However, contact Hitachi's sales office before using the product in an application that demands especially high quality and reliability or where its failure or malfunction may directly threaten human life or cause risk of bodily injury, such as aerospace, aeronautics, nuclear power, combustion control, transportation, traffic, safety equipment or medical equipment for life support.
4. Design your application so that the product is used within the ranges guaranteed by Hitachi particularly for maximum rating, operating supply voltage range, heat radiation characteristics, installation conditions and other characteristics. Hitachi bears no responsibility for failure or damage when used beyond the guaranteed ranges. Even within the guaranteed ranges, consider normally foreseeable failure rates or failure modes in semiconductor devices and employ systemic measures such as fail-safes, so that the equipment incorporating Hitachi product does not cause bodily injury, fire or other consequential damage due to operation of the Hitachi product.
5. This product is not designed to be radiation resistant.
6. No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without written approval from Hitachi.
7. Contact Hitachi's sales office for any questions regarding this document or Hitachi semiconductor products.

HITACHI

Hitachi, Ltd.
Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL
NorthAmerica : http:semiconductor.hitachi.com/
Europe : http://www.hitachi-eu.com/hel/ecg
Asia (Singapore) : http://www.has.hitachi.com.sg/grp3/sicd/index.htm
Asia (Taiwan) : http://www.hitachi.com.tw/E/Product/SICD_Frame.htm
Asia (HongKong) : http://www.hitachi.com.hk/eng/bo/grp3/index.htm
Japan : http://www.hitachi.co.jp/Sicd/indx.htm

For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose,CA 95134
Tel: <1> (408) 433-1990
Fax: <1>(408) 433-0223

Hitachi Europe GmbH
Electronic components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building. No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX